



# JOINT INSTITUTE

## 交大密西根学院

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## Introduction

VE311 Electronic Circuits (Fall 2021)

Dr. Chang-Ching Tu

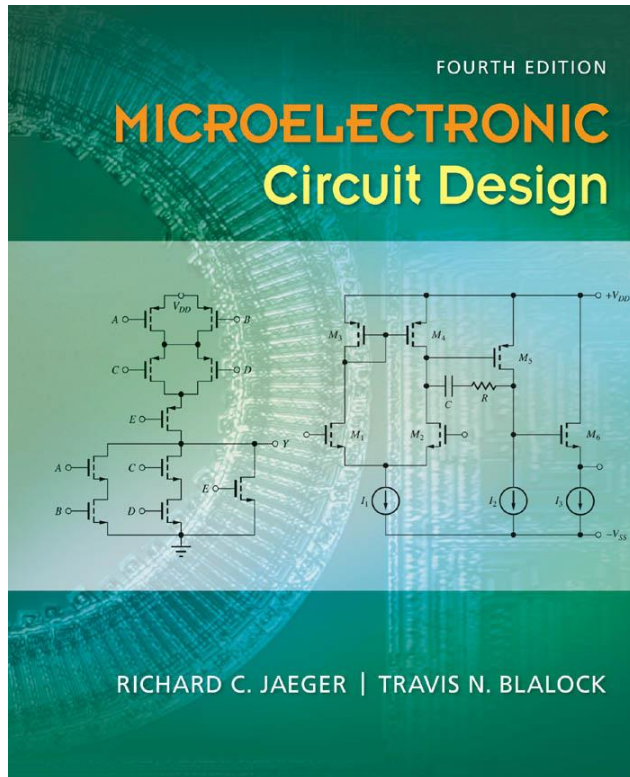
# Instructor Short Biography

- 台湾交通大学 (1998 – 2002)  
电子工程学系 B.S.
- 台湾交通大学 (2002 – 2004)  
电子工程学系 M.S.
- University of Washington, Seattle (2006 – 2011)  
Electrical Engineering, Ph.D.
- UW MSE Postdoc (2011 – 2012)
- LumiSands, Inc. Co-Founder / CEO (2013 – 2017)
- NCTU Applied Chemistry Postdoc (2014 – 2017)
- UM-SJTU JI Assistant Professor (2017 – 2021)
- UM-SJTU JI Associate Professor (2021 –)



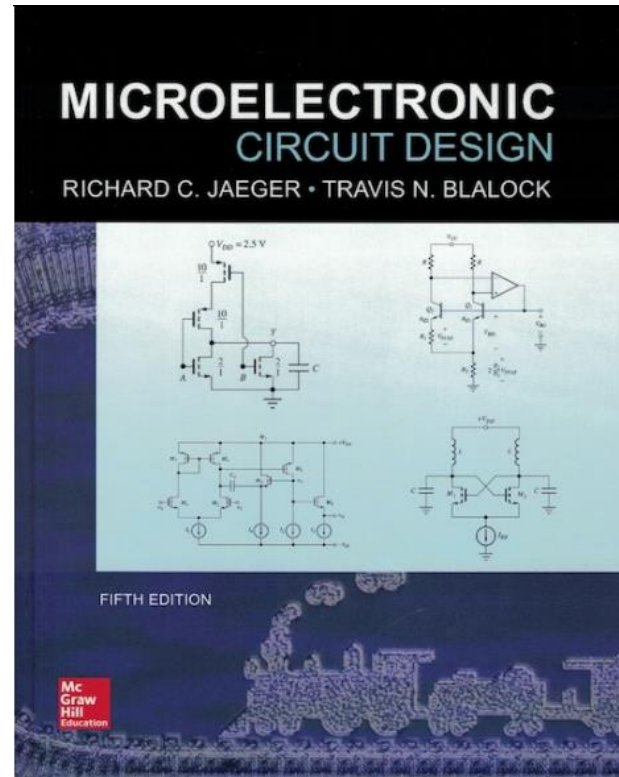
# Textbook I for Diode and BJT

3



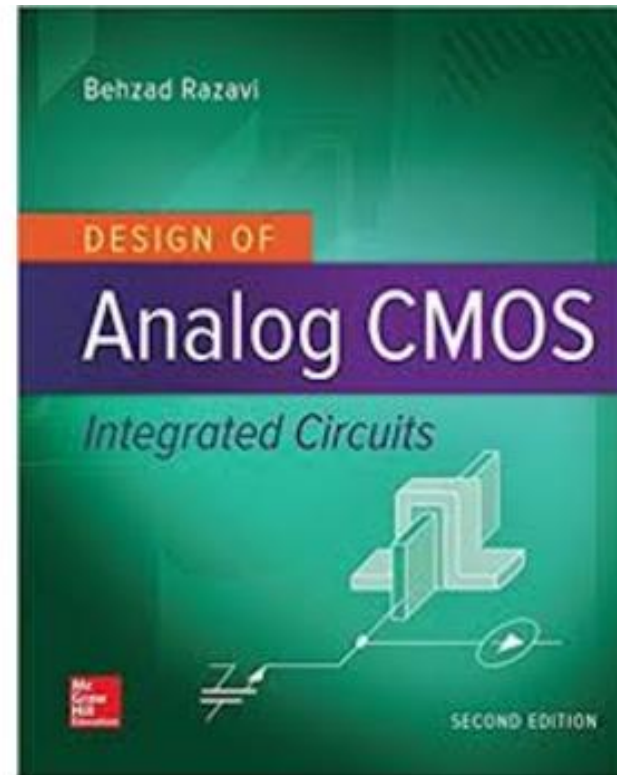
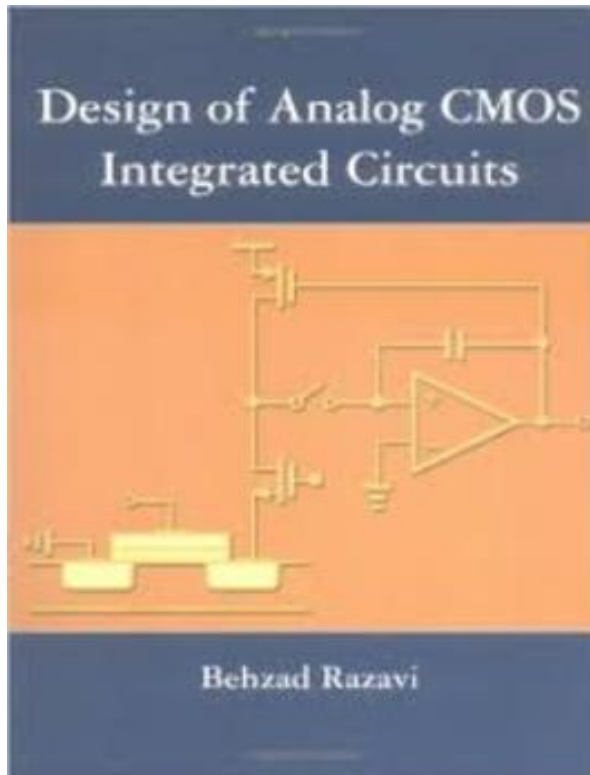
**Richard C. Jaeger**  
Distinguished University Professor Emeritus  
ECE Department  
Auburn University

**Travis N. Blalock**  
Visiting Associate Professor  
ECE Department  
University of Virginia



# Textbook II for MOSFET

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**Behzad Razavi**  
ECE Department  
UCLA

# Lectures

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## Midterm Exam



- Diode
  - Diode Circuit
  - BJT
  - BJT Circuit
  - MOSFET
- 
- MOSFET Single Stage Amplifiers
  - MOSFET Differential Amplifiers
  - Current Mirrors (If time allows)



**Final Exam**

## **Lab 1**

Diode Circuit  
(Rectifier)

## **Lab 2**

BJT Circuit  
(Single-stage  
amplifier)

## **Lab 3**

MOSFET Circuit  
(Single-stage  
amplifier)

## **Lab 4**

MOSFET Circuit  
(Differential pair  
amplifier +  
Feedback)

# Grading Policy

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- **8 × Assignments (with Pspice) (8%)**
- **4 × Lab Reports (Proteus + Lab) (12%)**
- **1 × Midterm Exam (34%)**
- **1 × Final Exam (42%)**
- **4 × Quizzes (4%)**

# IT Hardware Industry Ecosystem

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Apple  
HP  
Sony  
Huawei  
Samsung

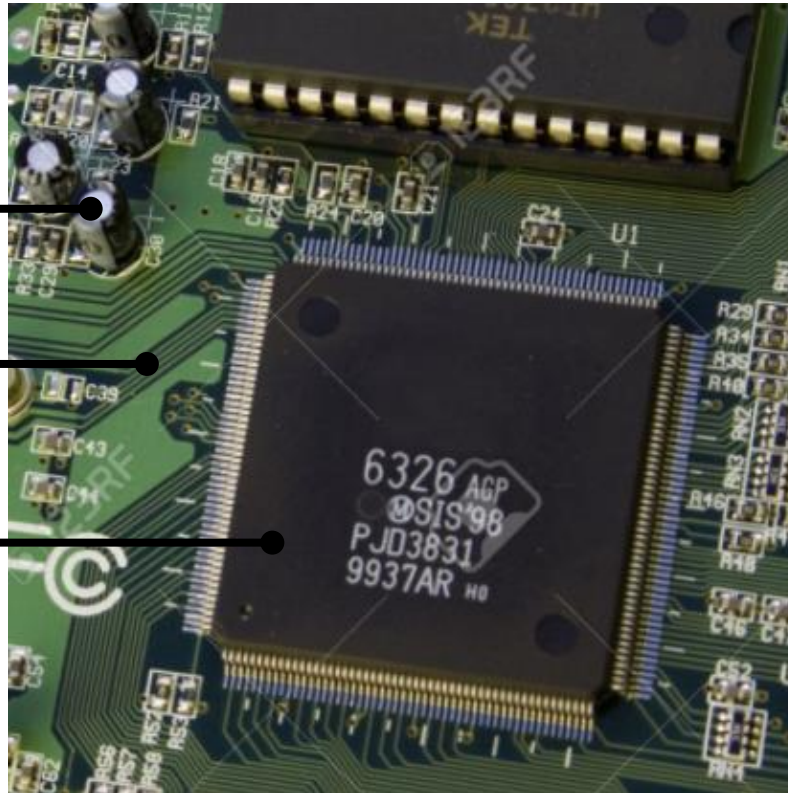
Apple  
Microsoft  
Google  
Amazon  
腾讯  
百度  
阿里巴巴



Capacitor/Resistor

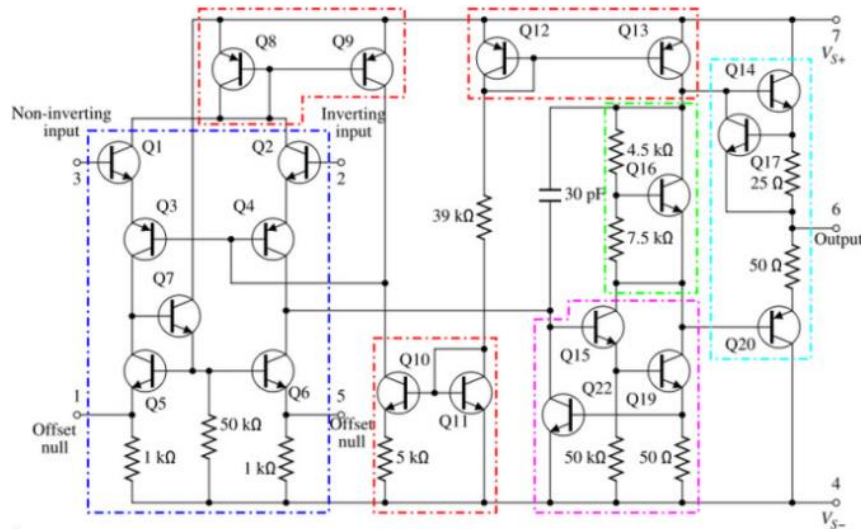
Printed Circuit  
Board (PCB)

Integrated Circuit  
(IC)

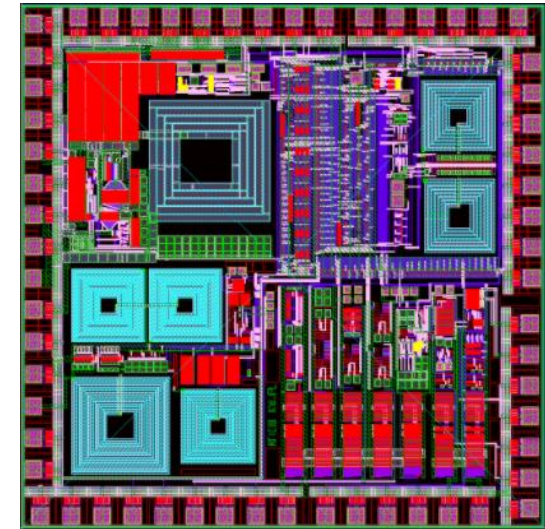


Foxconn  
Huawei  
Samsung

Qualcomm  
Broadcom  
MediaTek  
NVIDIA  
Marvell  
Apple  
Intel  
Huawei (海思)  
Samsung



Schematic  
(Spice)



Layout  
(Cadence)

[VE215](#): Introduction to Circuits

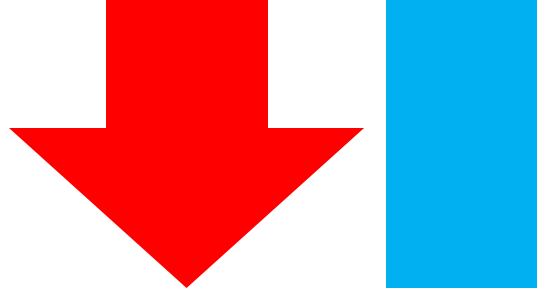
[VE311](#): Electronic Circuits

[VE312](#): Digital Integrated Circuits

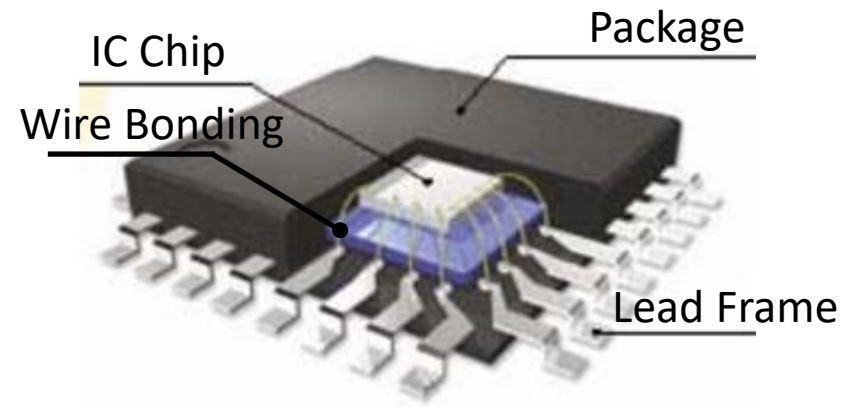
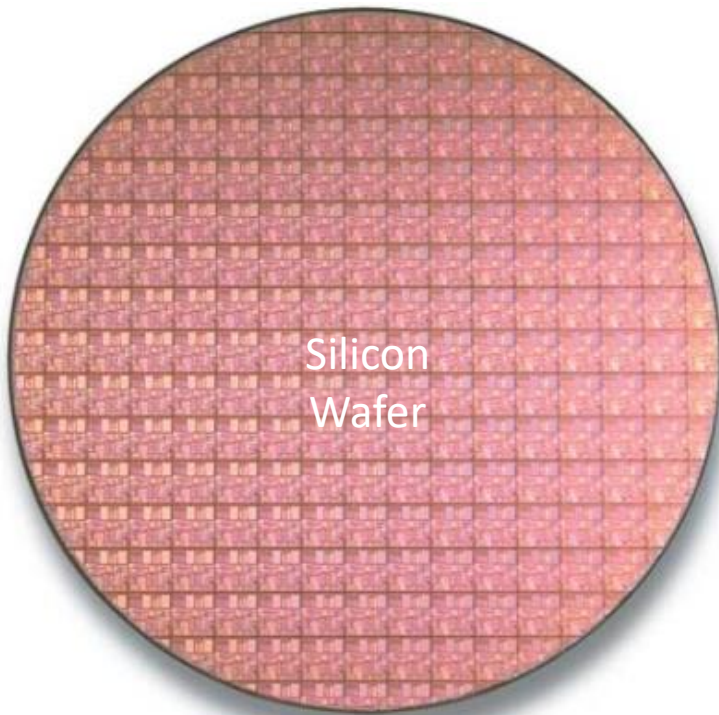
[VE411](#): Microwave Circuits I

[VE413](#): Monolithic Amplifier Circuits

[VE427](#): VLSI Design I



TSMC  
Intel  
GlobalFoundries  
Samsung  
中芯半导体



[VE320](#): Introduction to Semiconductor Devices

[VE421](#): Properties of Transistors

# Top IC Design Companies

**Table: 2019 Revenue Ranking of Top 10 IC Design Companies (Unit: Million USD)**

Ranking	Company	2019 Revenue	2018 Revenue	YoY
1	Broadcom	17,246	18,547	-7.0%
2	Qualcomm	14,518	16,370	-11.3%
3	NVIDIA	10,125	11,163	-9.3%
4	MediaTek	7,962	7,882	1.0%
5	AMD	6,731	6,475	4.0%
6	Xilinx	3,236	2,868	12.8%
7	Marvell	2,708	2,823	-4.1%
8	Novatek	2,085	1,813	15.0%
9	Realtek	1,965	1,518	29.4%
10	Dialog	1,421	1,442	-1.5%
<b>Top 10 Total</b>		<b>67,997</b>	<b>70,901</b>	<b>-4.1%</b>

Source: TrendForce, March, 2020

联发科

联咏  
瑞昱



# Top IC Manufacturers

**Table: Ranking of the Global Top 10 Foundries by Revenue, 1Q20 (Unit: Million USD)**

Ranking	Company	1Q20E	1Q19	YoY	M/S
1	TSMC	10,200	7,096	43.7%	54.1%
2	Samsung	2,996	2,586	15.9%	15.9%
3	GlobalFoundries	1,452	1,256	15.6%	7.7%
4	UMC	1,397	1,057	32.2%	7.4%
5	SMIC	848	669	26.8%	4.5%
6	TowerJazz	300	310	-3.3%	1.6%
7	VIS	258	224	14.9%	1.4%
8	PSMC	251	178	41.2%	1.3%
9	Hua Hong	200	221	-9.4%	1.1%
10	DB HiTek	158	139	13.8%	0.8%
<b>Top 10 Total</b>		<b>18,060</b>	<b>13,737</b>	<b>31.5%</b>	<b>95.7%</b>

Source: TrendForce, March, 2020

Our World  
in Data

## Transistor count

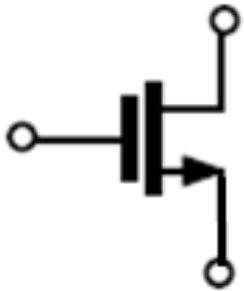


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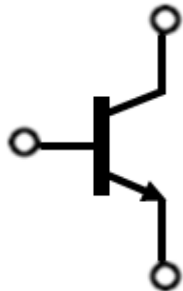
# Active vs Passive Components

## Active Components

MOSFET



BJT



Diode



VE 311

## Passive Components

Resistor



Capacitor



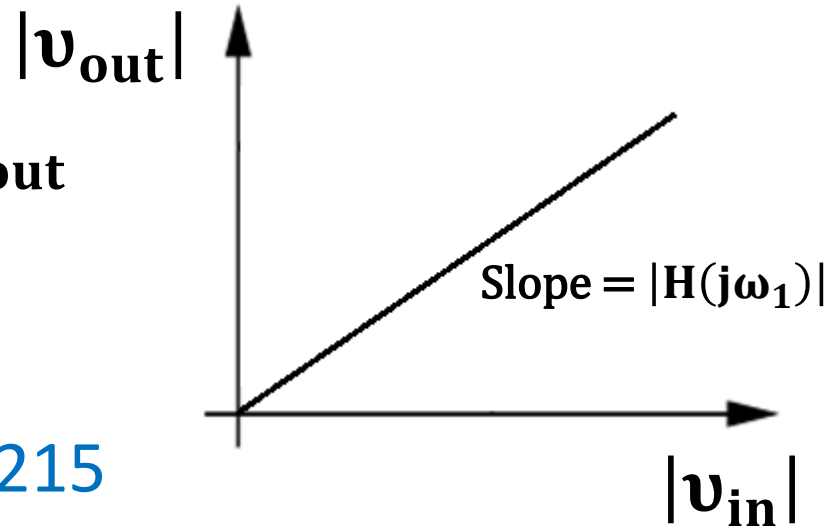
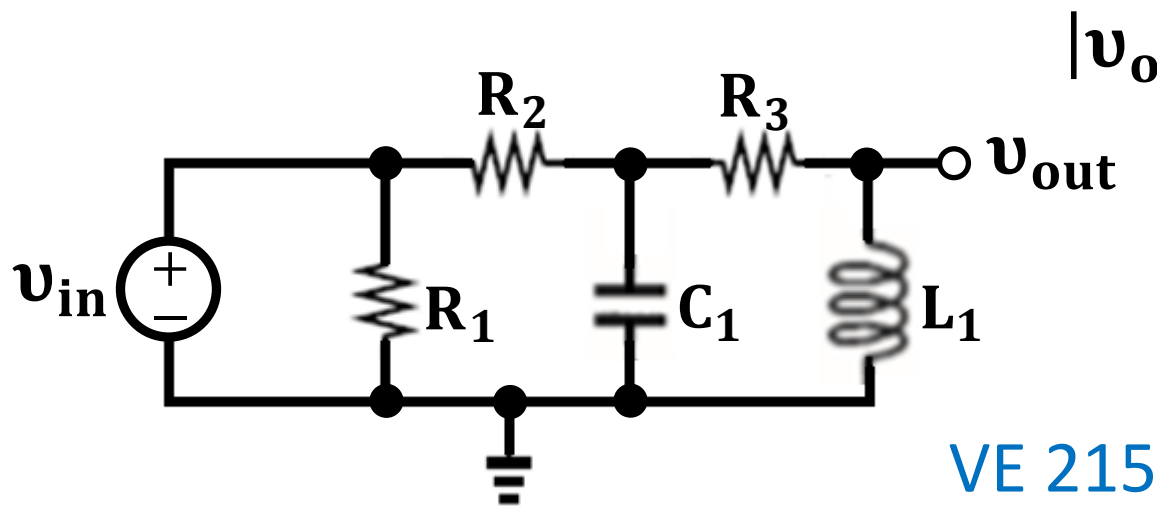
Inductor



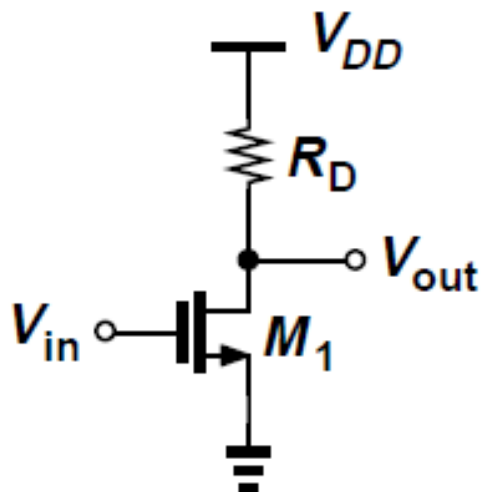
VE 215

# Linear vs Nonlinear Circuit

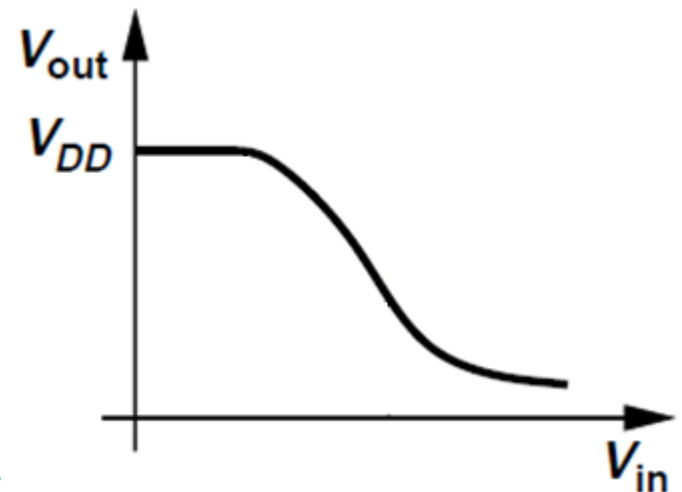
## Linear Circuit



## Nonlinear Circuit



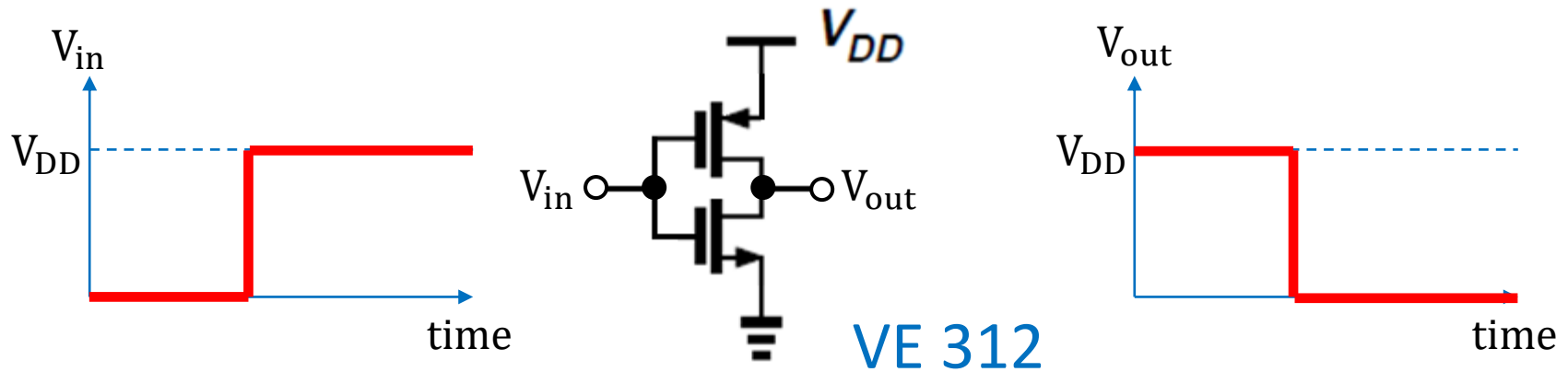
VE 311



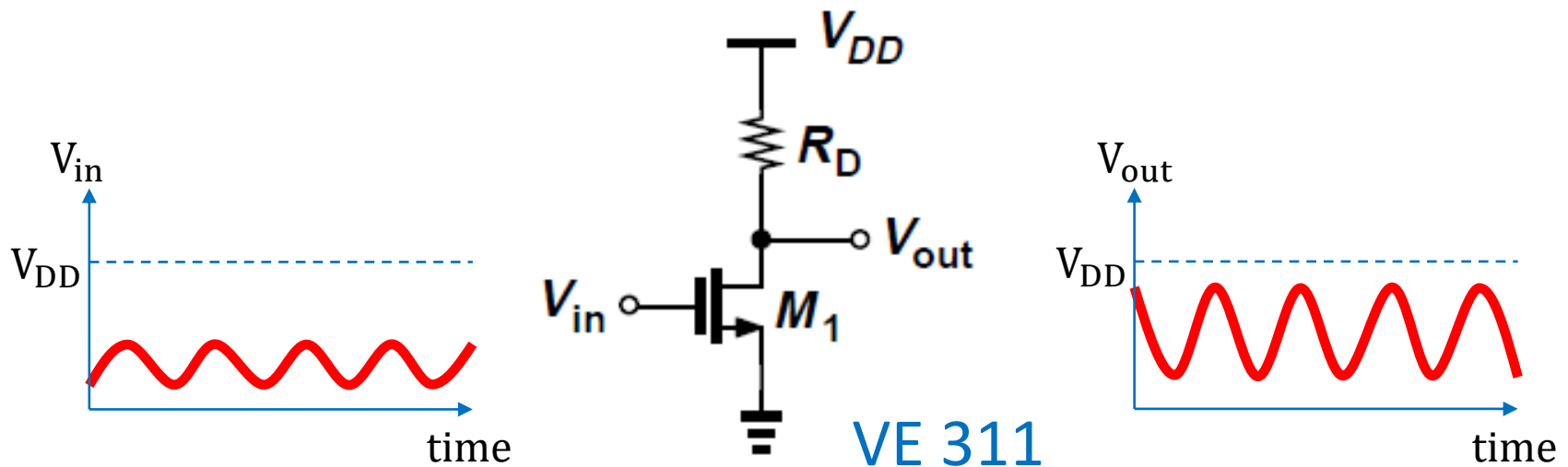


# Analog vs Digital

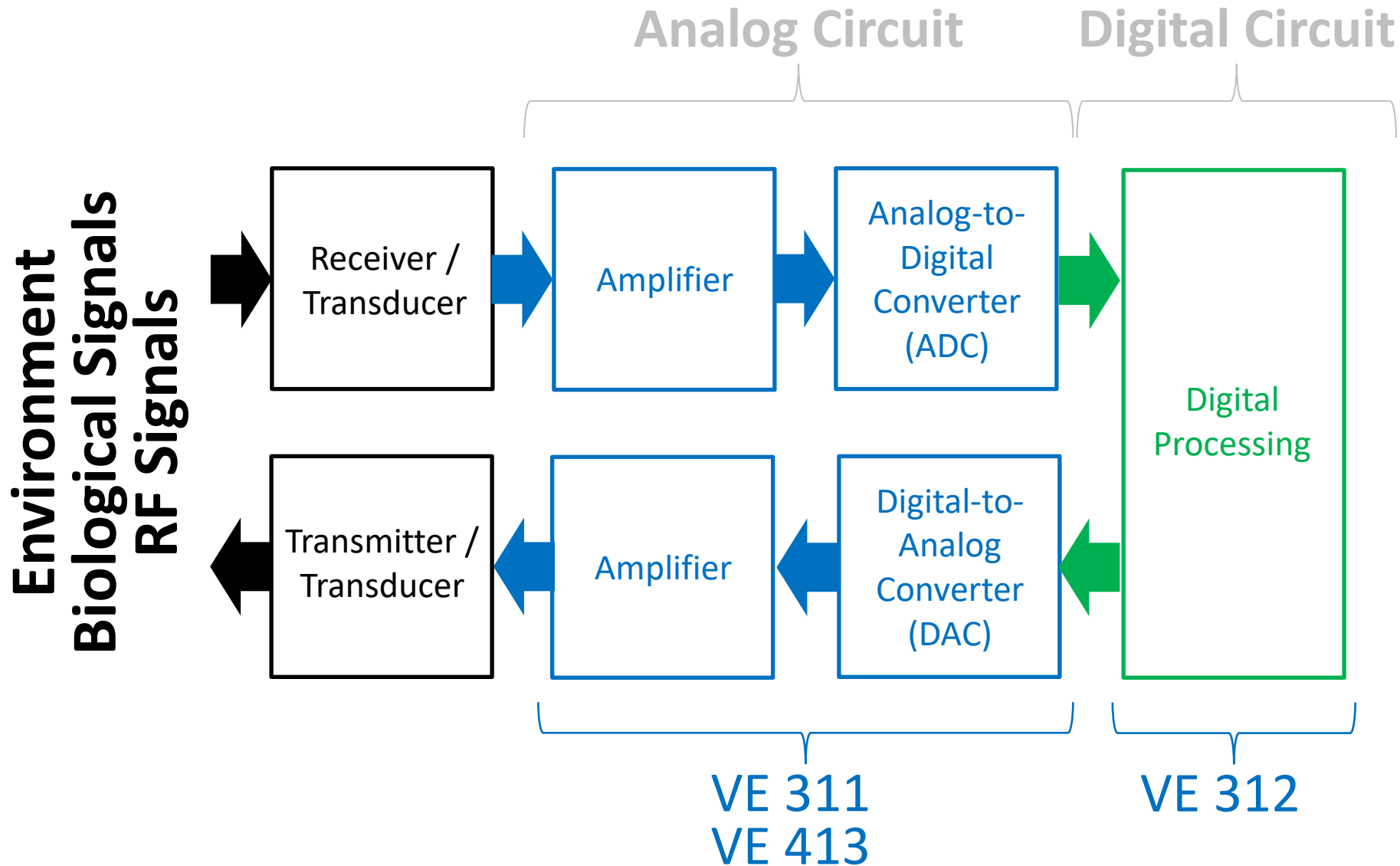
## Digital



## Analog



# Analog Circuit in IC



# IC Design Process

**Hand calculations** on paper,  
based on proper approximations.



**Pre-simulation:** Schematic  
design and simulation on Spice.



**Post-simulation:** Layout  
drawing, simulation and design  
rule check on Cadence.



**Tapeout:** Layout design sent to  
IC manufacturers.

VE 311